

SOT684-3

plastic thermal enhanced very thin quad flat package; no leads; 56 terminals; body 8 x 8 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN56
Package type industry code	HVQFN56
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
Mounting method type	S (surface mount)
Issue date	11-3-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	7.9	-	8	8.1	mm
E	package width	7.9	-	8	8.1	mm
A	seated height	0.8	-	0.85	1	mm
A ₂	package height	[tbd]	-	0.85	[tbd]	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	56	-	

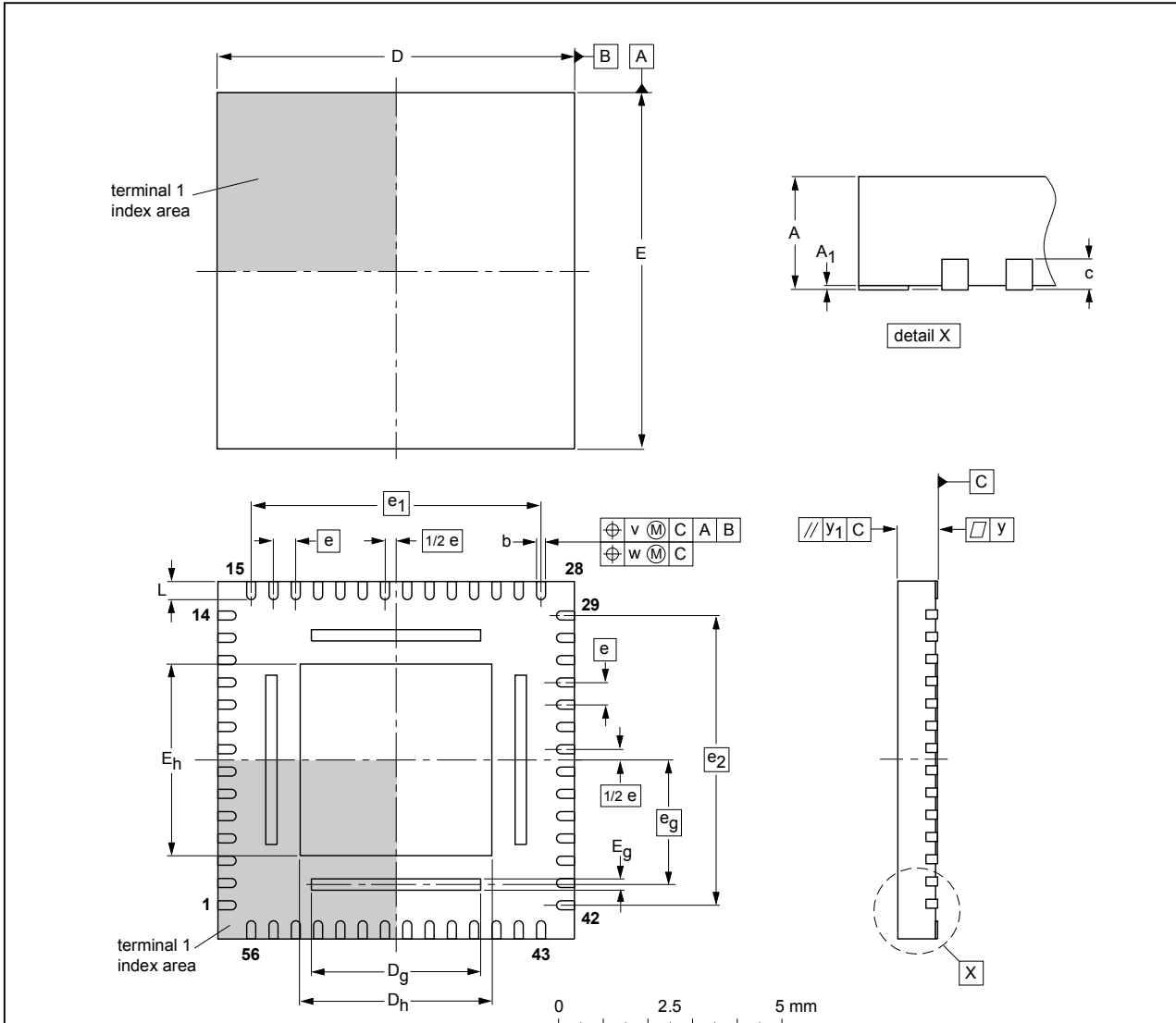


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2. Package outline

HVQFN56: plastic thermal enhanced very thin quad flat package; no leads; 56 terminals; body 8 x 8 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾ max.	A ₁	b	c	D ⁽¹⁾	D _g	D _h	E ⁽¹⁾	E _g	E _h	e	e ₁	e ₂	e _g	L	v	w	y	y ₁
mm	1	0.05 0.00	0.30 0.18	0.2	8.1 7.9	3.85 3.75	4.35 4.25	8.1 7.9	0.25	4.35 4.25	0.5	6.5	6.5	2.8	0.5 0.3	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT684-3	---	MO-220	---		03-03-11

Fig. 1. Package outline HVQFN56 (SOT684-3)

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3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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